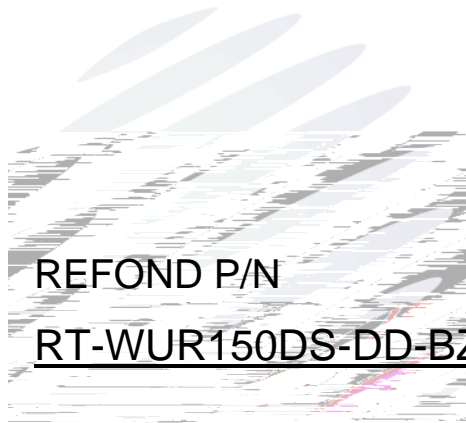


SPECIFICATION



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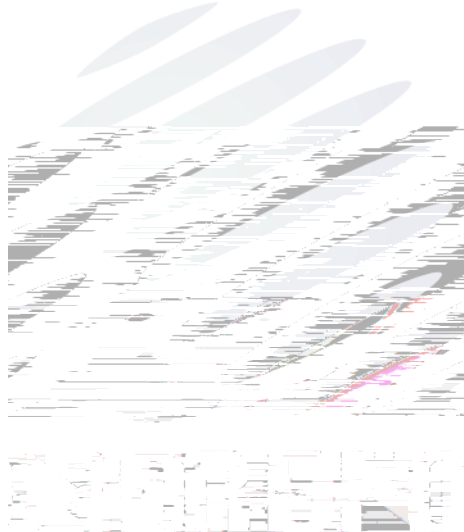
1. Description 他

1.1 General Description

The White LED, which was fabricated by using a blue chip and the phosphor.

Product Package:3.2mmX1.25mmX1.1mm.

P 9C 9 C 9 C 3 4PM BC M LB B M B B



1.4 Package Dimension

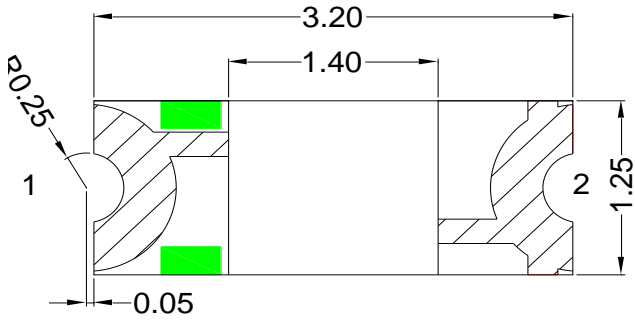


Fig.1-1 Top view

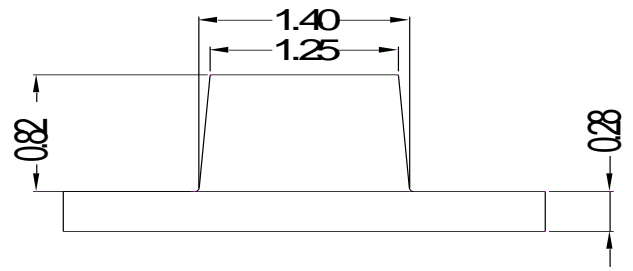


Fig.1-2 Side view

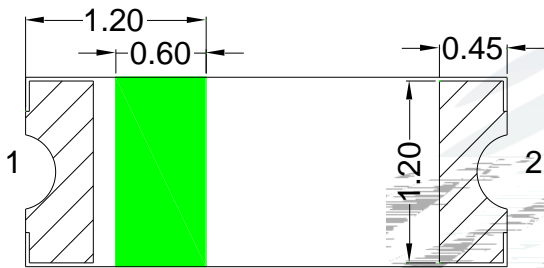


Fig.1-3 Bottom view

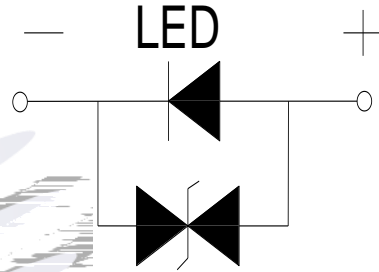


Fig.1-4 Polarity

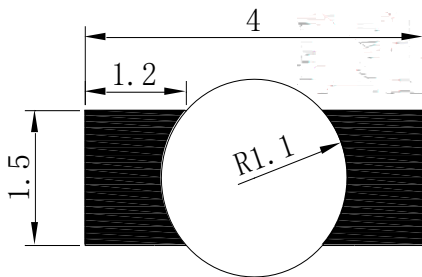


Fig.1-5 Soldering patterns

Notes

1. All dimensions units are millimeters.
2. All dimensions tolerances are $\pm 0.2\text{mm}$ unless otherwise noted.



1.5 Product Parameters 反

Table 1-1 Electrical / Optical Characteristics at Ts=25°C 丙

Item	Test Condition	Symbol	Value			Unit 占	
			Min. ()	Typ.	Max.		
Forward voltage 正向电压	I _F =5mA	V _F	E2	2.5	--	2.6	V
			F1	2.6	--	2.7	V
			F2	2.7	--	2.8	V
			G1	2.8	--	2.9	V
			G2	2.9	--	3.0	V
			H1	3.0	--	3.1	V
			H2	3.1	--	3.2	V
Luminous intensity 发光强度	I _F =5mA	I _v	G00	100	--	150	mcd
			H00	150	--	230	mcd
			I00	230	--	350	mcd
Viewing angle at 50% I _v 发光角度	I _F =5mA	1 0.1	--	140	--	deg	
Reverse current 漏电流	V _R =5V	I _R	--	--	10	μA	
Thermal resistance 热阻	I _F =5mA	R _{THJS}	--	--	450	°C/W	
Reverse voltage 反向电压	I _R =10mA	V _R	5	--	10	V	

 Notes : V_R=5V For test conditions. V_R=5V


1. 1/10 Duty cycle, 0.1ms pulse width.



2. The above forward voltage measurement allow6P 4 4-9(-)-7C BT/F3 10.56 TC B2tached [/Top]/Type/Paginat± 8y31 T



1.6 Bin Range Of Forward Voltage and Luminous Flux (IF=5mA) 丙
 BIN (IF=5mA)

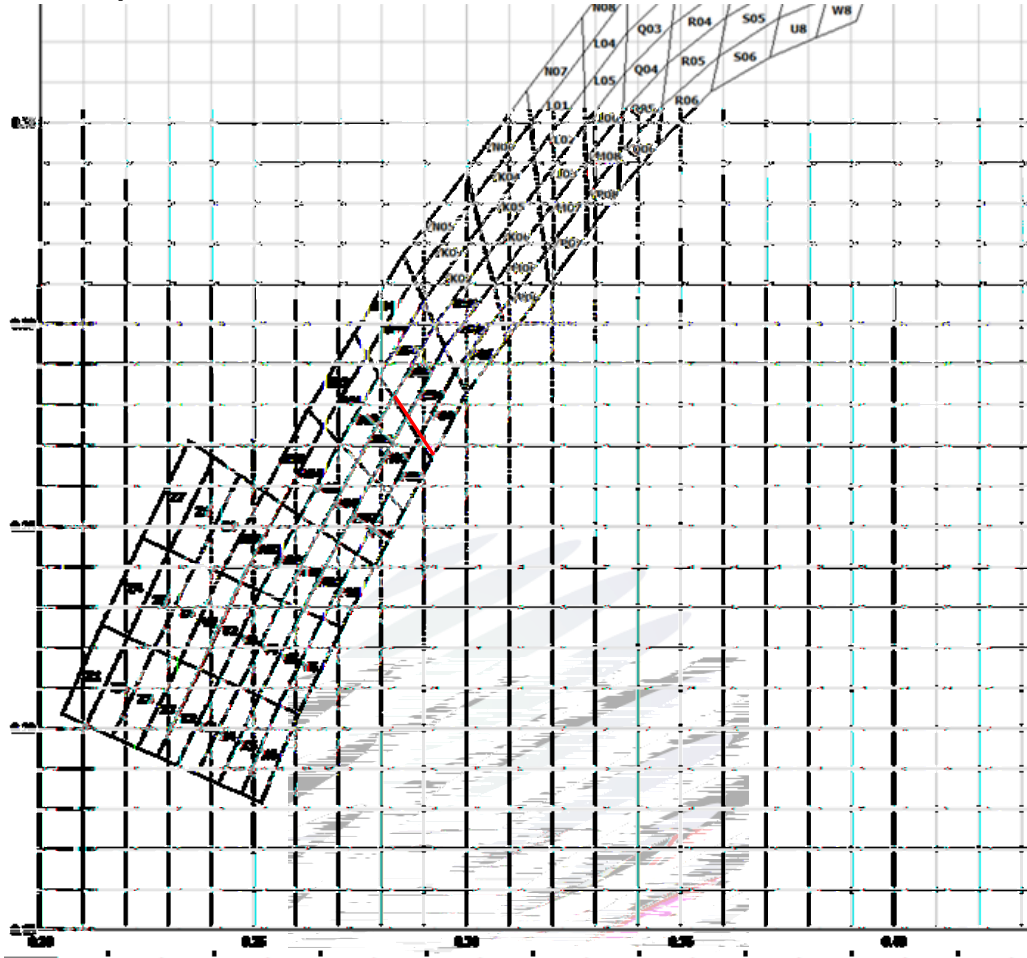


Fig. 1-6 The C.I.E Chromaticity Diagram CIE

Table 1-3 Bin Date Bin

BIN CODE	CIE-X1	CIE-Y1	CIE-X2	CIE-Y2	CIE-X3	CIE-Y3	CIE-X4	CIE-Y4
B06								
K03								
K06								
M04								
M05								
M06								
P04								
P05								
P06								



1.7 Typical Optical Characteristics Curves

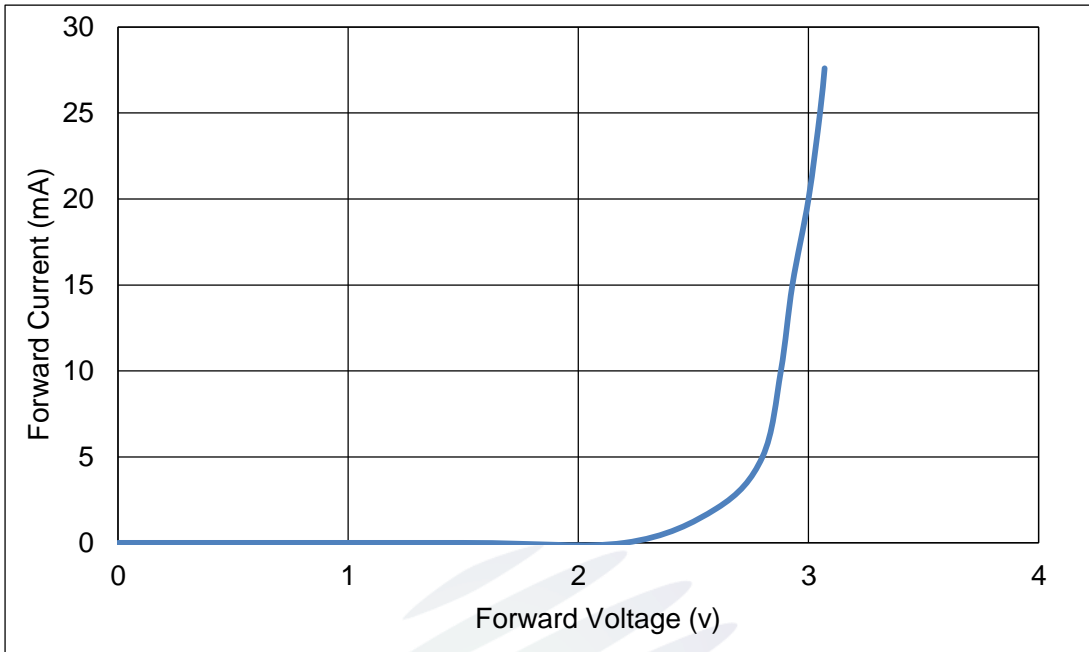


Fig 1-7 Forward Voltage Vs Forward Current

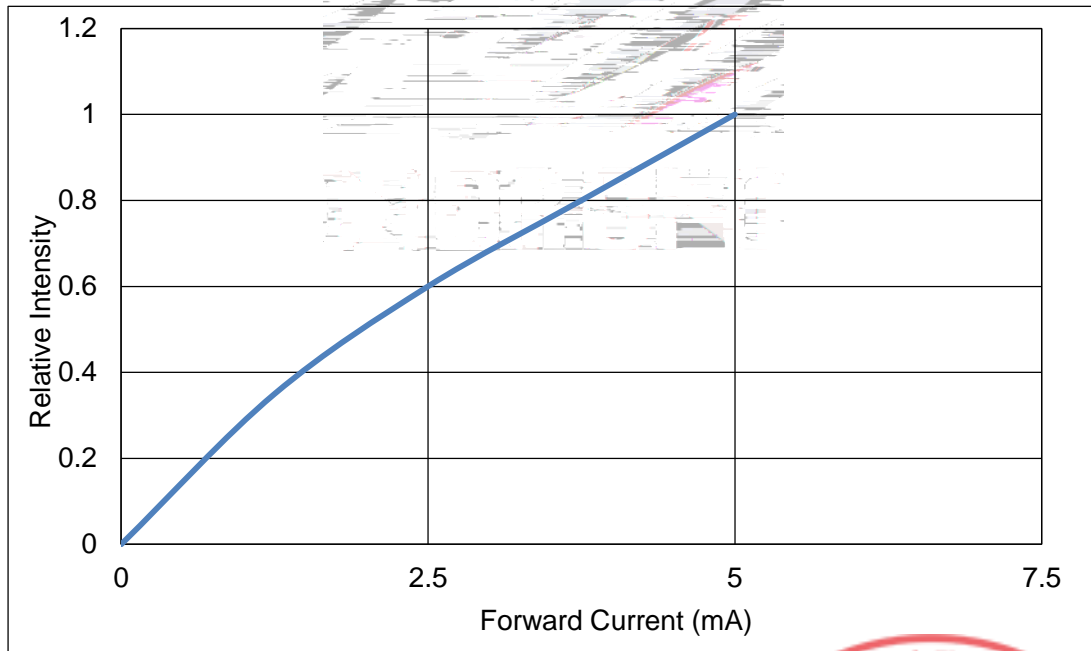


Fig 1-8 Forward Current Vs Relative Intensity



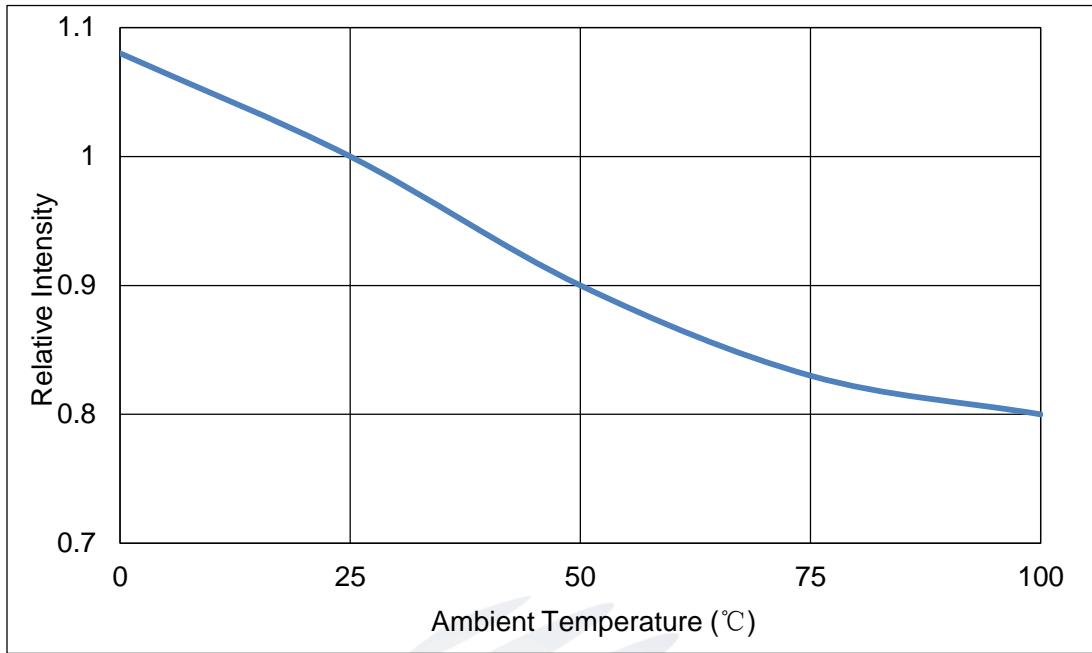


Fig 1-9 Pin Temperature Vs Relative Intensity 丙射

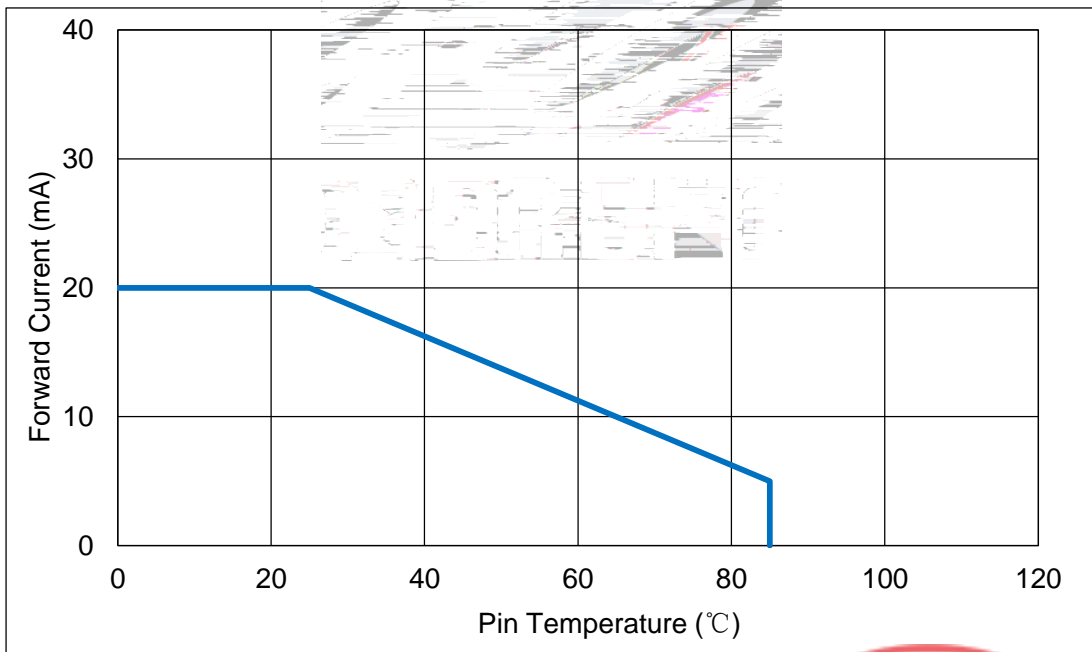


Fig 1-10 Pin Temperature Vs Forward Current



Fig.1-11 Forward Current Vs Dominate Wavelength (Ta=25°C)

丙

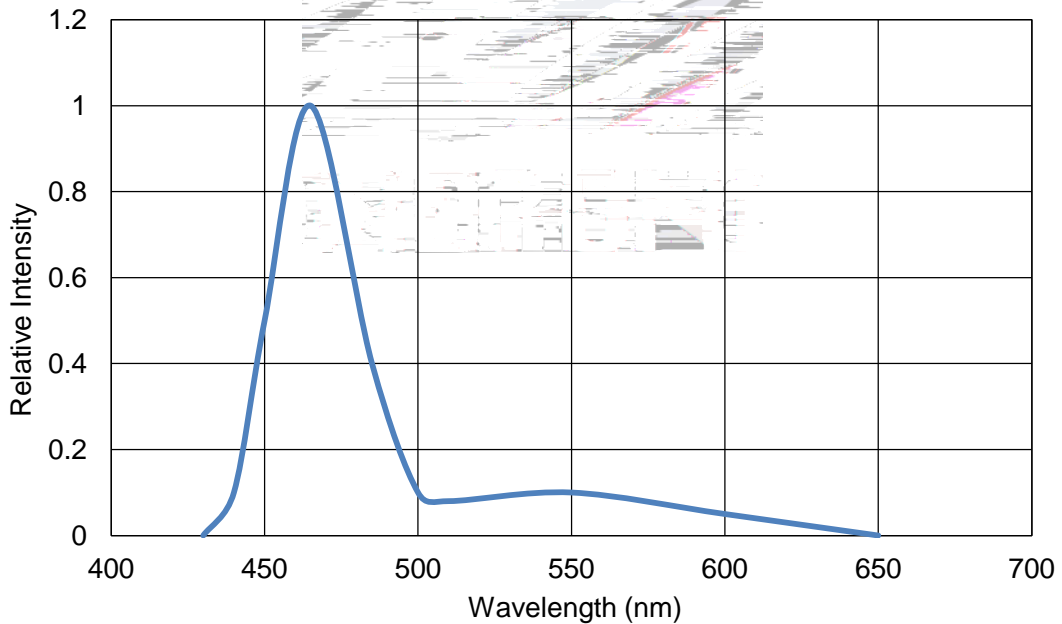


Fig.1-12 Relative Intensity Vs Wavelength (Ta=25°C)

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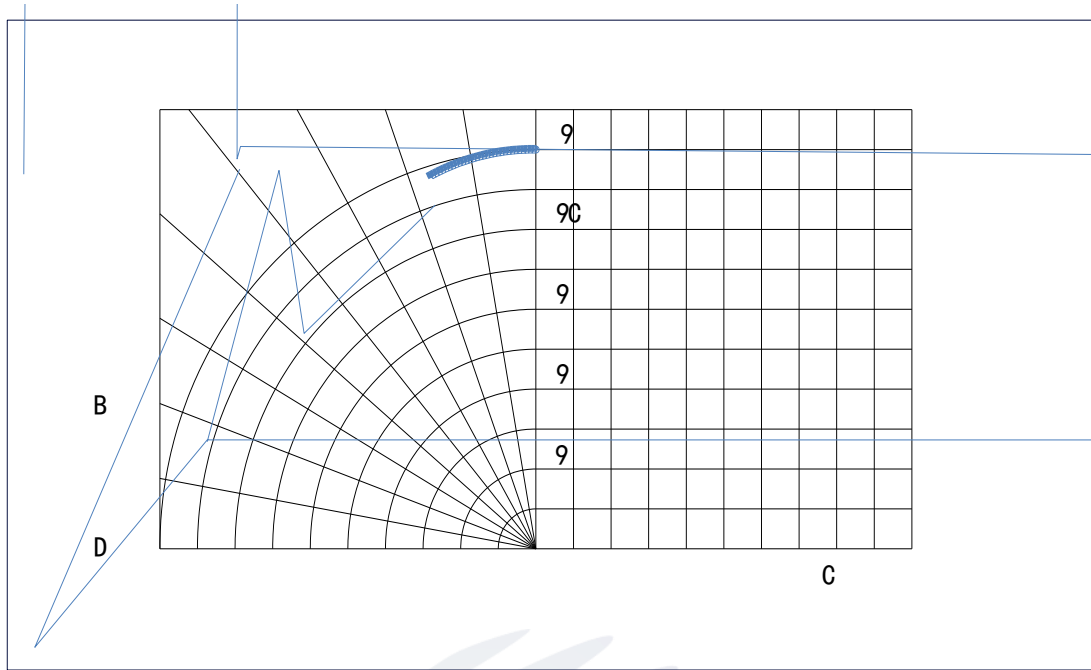
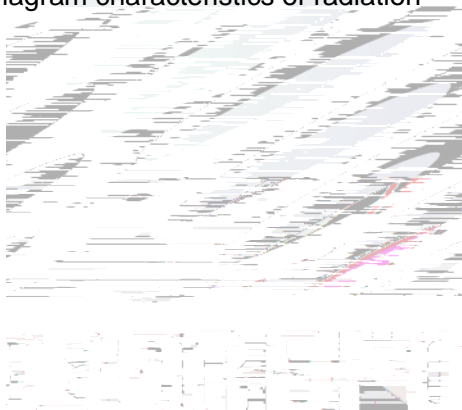


Fig.1-13 Diagram characteristics of radiation



2. Packaging

2.1 Packaging Specification

Package:3000pcs/reel. 3000pcs

2.1.1Carrier Tape Dimension

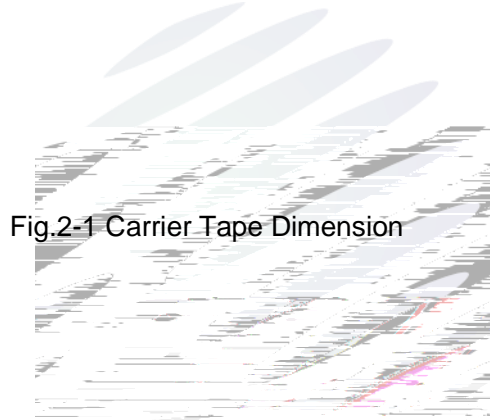


Fig.2-1 Carrier Tape Dimension

2.1.2Reel Dimension



Table 2-1 Dimension

2.1.3 Label Form Specification

Table 2-2 Parameter 反

PART NO:		
SPEC NO:		
LOT NO		
BIN CODE:		
Φ:	XY:	
VF:	WLD:	
	QTY:	
	DATE:	

PART NO.	Part Number
SPEC NO.	Spec Number
LOT NO.	Lot Number
BIN CODE	Bin Code 反
	Luminous flux
XY	Chromaticity Bin
V _F	Forward Voltage
WLD	Wavelength
QTY	Packing Quantity
DATE	Made Date

Fig. 2-3 Label Form Specification

2.2 Moisture Resistant Packing

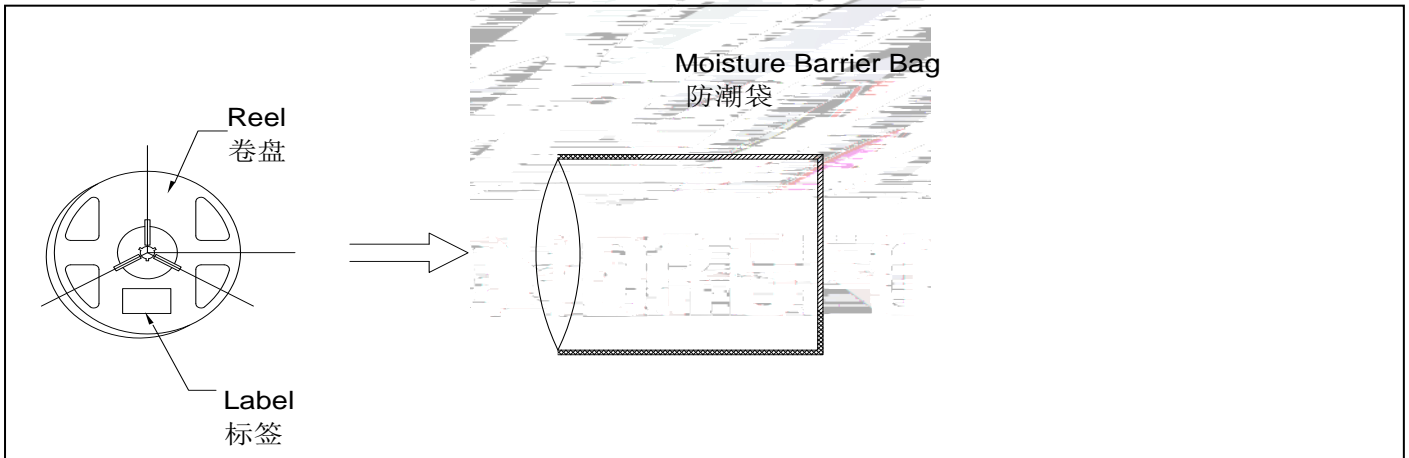


Fig.2-4 Moisture Resistant Packing



2.3 Cardboard Box

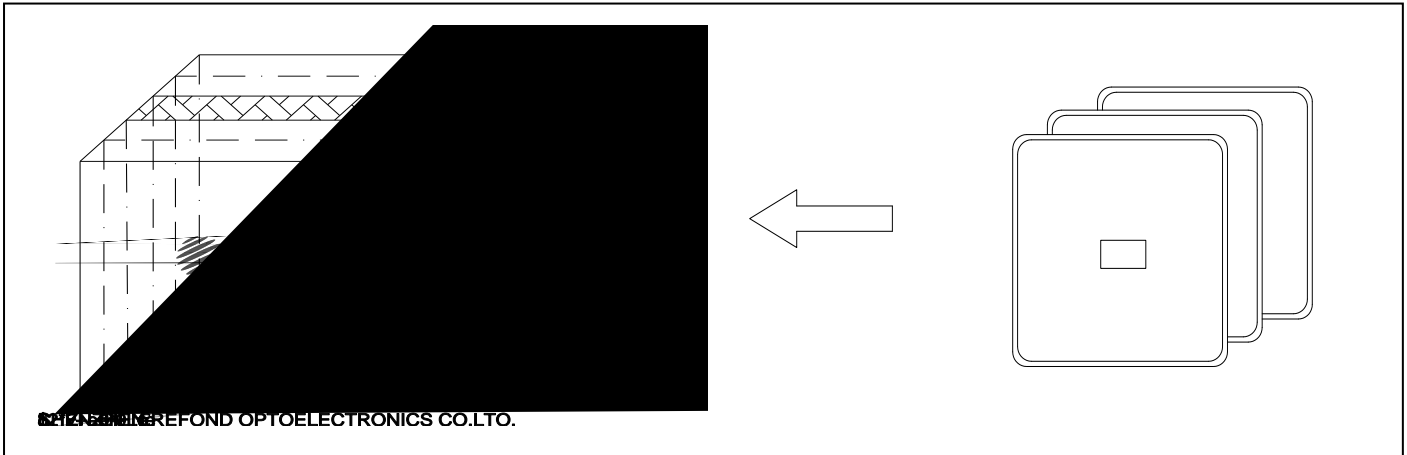
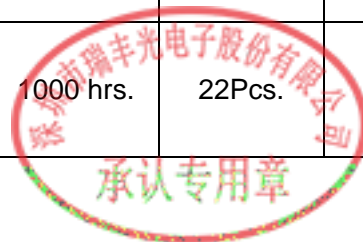


Fig.2-5 Cardboard Box

2.4 Reliability Test Items And Conditions

Table 2-3 Reliability Test Items And Conditions

Test Items	Ref. Standard 反	Test Condition	Time	Quantity	Ac/Re /
Reflow	JESD22-B106	Temp:260 max T=10 sec	2 times	22Pcs.	0/1
Temperature Cycle	JESD22-A104	100 30 min 5 min -40 30 min	100 cycles	22Pcs.	0/1
Thermal Shock 分	JESD22-A106	-40 15min 100 15min	300 cycles	22Pcs.	0/1
High Temperature Storage	JESD22-A103	Temp:100	1000 hrs.	22Pcs.	0/1
Low Temperature Storage	JESD22-A119	Temp:-40	1000 hrs.	22Pcs.	0/1
Life Test	JESD22-A108	T _a =25 I _F =5mA	1000 hrs.	22Pcs.	0/1



2.5 Criteria For Judging Damage

Table 2-4 Criteria For Judging Damage

Test Items	Symbol	Test Condition	Criteria For Judgement	
			Min.	Max.
Forward Voltage	V_F	$I_F=5mA$	-	U.S.L*)x1.1
Reverse Current	I_R	$V_R= 5V$	-	U.S.L*)x2.0
Luminous Flux		$I_F=5mA$	L.S.L*)x0.7	-

Notes



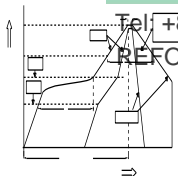
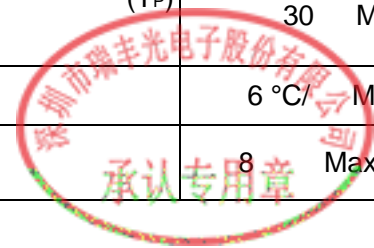
3. SMT Reflow Soldering Instructions SMT 回流焊说明

3.1 SMT Reflow Soldering Instructions SMT

Fig.3-1 SMT Reflow Soldering Instructions SMT

Table 3-1 Parameter 反

Average temperature rise speed	$T_{smax} - T_P$	3 °C/ Max 3 °C/ s
Preheating: minimum temperature	(T_{smin})	150 °C
Preheating: Max temperature	(T_{smax})	200 °C
Preheating: Time	$T_{smin} - T_{smax}$	60 - 120 60s-120s
Time limited to maintain high temperature: the temperature	(T_L)	217 °C
Time limited to maintain high temperature: The Time	(t_L)	60 - 150 60s-150s
Peak /Classification of temperature:	(T_P)	260 °C
Time limit classification of peak temperature time	t_p	10 Max 10s
Hold time within 5 °C with the actual peak temperature (TP) 丙	(T_P)	30 Max 30s
Cooling speed		6 °C/ Max 6 °C/ s
Needed time from 25 °C to $T_{p25} °C$		8 Max 8 minutes



(1)Reflow soldering should not be done more than twice. If more than 24 hours between the two solderings , LED will be damaged. P

(2)Whensoldering , do not put stress on the LEDs during heating.

3.1.1 Soldering Iron

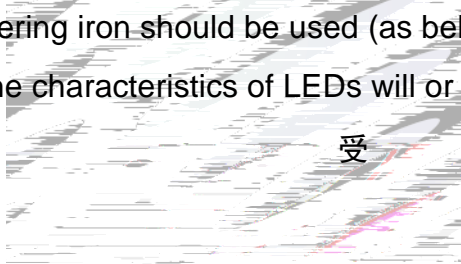
(1) When do soldering by hand, keep the temperature of iron below less 300 less than 3 seconds. 7

(2) Soldering by hand should be done only one time. 下

3.1.2 Repairing

Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable,a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or not be damaged by repairing.

LED
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3.1.3 Cautions

(1) Components should not be mounted on warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board.LED M

(2) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.

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4. Handling Precautions

4.1 Handling Precautions

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement. LED 丙 P 9

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(2) In order to prevent ex-ternal material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM, the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement. P P

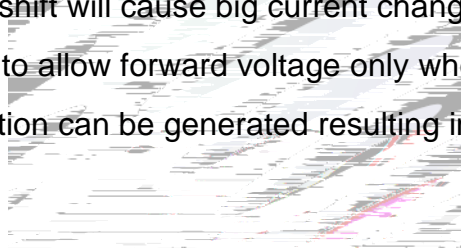


(4) Handle the component along the side surface by using forceps or appropriate tools; Do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.

Fig 4-1 Handling Precautions 产品使用注意事项

(5) In designing a circuit, the current through each LED can not exceed the absolute maximum rating specified for each LED. In the mean while, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage.

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(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design. LED

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(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust, requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the

LED. 丙

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Table 4-1 Storage

Conditions		Temperature	Humidity	Time
Storage	Before Opening Aluminum Bag	30	75%	Within 1 Year From Date 下
	After Opening Aluminum Bag	30	60%	168hours 168
Baking		60 5	-	24hours 24

(8) If the moisture absorbent material silica gel has faded away or the LEDs have exceeded the storage time, baking treatment should be performed after unpacking and based on the following condition 60 5 for above 24 hours. 前

If the package is flatulence or damaged, please notify the sales staff to assist.

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(9) Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS). 单 下 P 射 分

(10) Other points for attention, please refer to our relevant information.

反 主





Declare

This specification is written both in English and in Chinese and the latter is formal.

